

Resource Summary Report

Generated by Kravitz on Sep 10, 2026

Intel

RRID:SCR_016973

Type: Tool

Proper Citation

Intel (RRID:SCR_016973)

Resource Information

URL: <https://www.intel.com/content/www/us/en/homepage.html>

Proper Citation: Intel (RRID:SCR_016973)

Description: American multinational corporation and technology company headquartered in Santa Clara, California, in the Silicon Valley. Semiconductor chip maker being overtaken by Samsung. Inventor of the x86 series of microprocessors, the processors found in most personal computers (PCs). Intel supplies processors for computer system manufacturers such as Apple, Lenovo, HP, and Dell. Intel also manufactures motherboard chipsets, network interface controllers and integrated circuits, flash memory, graphics chips, embedded processors and other devices related to communications and computing.

Abbreviations: Intel

Synonyms: Intel Corporation, intel, Intel

Resource Type: commercial organization

Keywords: Commercial, organization, semiconductor, chip, microprocessor, manufacture, supply

Resource Name: Intel

Resource ID: SCR_016973

Alternate IDs: Wikidata: Q248, Crossref funder ID: 100002418, ISNI: 0000 0004 1217 7655, grid.419318.6

Alternate URLs: <https://ror.org/01ek73717>

Record Creation Time: 20220129T080333+0000

Record Last Update: 20260905T132816+0000

Ratings and Alerts

No rating or validation information has been found for Intel.

No alerts have been found for Intel.

Data and Source Information

Source: [SciCrunch Registry](#)

Usage and Citation Metrics

We found 2 mentions in open access literature.

Listed below are recent publications. The full list is available at [Kravitz](#) .

Singh P, et al. (2024) Frontiers in Three-Dimensional Surface Imaging Systems for 3D Face Acquisition in Craniofacial Research and Practice: An Updated Literature Review. Diagnostics (Basel, Switzerland), 14(4).

Zhao Y, et al. (2022) A statistical learning protocol to resolve the morphological complexity of two-dimensional macromolecules. STAR protocols, 3(4), 101767.